

IN THE CLAIMS:

Claims 1-13 have been amended herein. All of the pending claims 1 through 13 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) A clamping method for attaching a portion of a wire to a portion of at least one lead finger of a lead frame using a clamp in a wire bonding apparatus having a heat block for supporting ~~said the~~ at least one lead finger during a wire bonding operation comprising:
providing an independently movable clamp for movement in at least one x-axis direction, at least one y-axis direction, and at least one z-axis direction; and
positioning ~~said the~~ independently movable clamp over a portion of ~~said the~~ at least one lead finger for clamping ~~said the~~ at least one lead finger in position on a portion of ~~said the~~ heat block for attaching of at least ~~said the~~ portion of ~~said the~~ wire thereto during a wire bond operation of ~~said the~~ wire bonding apparatus.
2. (Currently Amended) The clamping method of claim 1, further comprising:
actuating ~~said the~~ wire bonding apparatus for ~~bonding attaching~~ ~~said the~~ portion of ~~said the~~ wire to ~~said the~~ at least one lead finger.
3. (Currently Amended) The clamping method of claim 2, further comprising:
disengaging ~~said the~~ independently movable clamp from ~~said the~~ portion of ~~said the~~ at least one lead finger before removal of ~~said the~~ wire bonding apparatus from ~~said the~~ at least one lead finger on ~~said the~~ heat block.
4. (Currently Amended) The clamping method of claim 1, wherein ~~said the~~ independently movable clamp comprises a resiliently mounted clamp.

5. (Currently Amended) ~~An attachment~~ A method for attaching a portion of a wire to a portion of a lead finger of a lead frame using a first clamp and an independently movable clamp in a wire bonding apparatus having a heat block comprising:

positioning-a the first clamp over-a the portion of-said the lead finger for clamping-said the lead finger in a position on-said the heat block during-said ~~bonding~~ attaching-said the portion of-said the wire thereto,-said the first clamp comprising a clamp movable in at least one x-axis direction, at least one y-axis direction, and at least one z-axis direction; and positioning-an-independent the independently movable clamp over another portion of-said the lead finger for retaining-said the lead finger in-said the position on-a the portion of-said the heat block during-said ~~bonding~~ attaching of-said the wire thereto.

6. (Currently Amended) The method of claim 5, further comprising: actuating apparatus for ~~bonding-said~~ attaching the portion of-said the wire to-said the portion of ~~said~~ the lead finger in-said the wire bonding apparatus.

7. (Currently Amended) The method of claim 6, further comprising: removing-said-independent the independently movable clamp from engagement with-said the portion of-said the lead finger before removal of-said the wire bonding apparatus from ~~said~~ the lead finger.

8. (Currently Amended) The method of claim 5, wherein-said-independent the independently movable clamp comprises a resiliently mounted clamp.

9. (Currently Amended) A method for attaching at least a portion of a wire to a portion of a lead finger of a lead frame using a plurality of clamps in a wire bonding apparatus having a heat block comprising: positioning a first independent clamp over-a the portion of-said the lead finger for retaining-said the lead finger on a portion of-said the heat block for bonding a portion of-said the wire

thereto, ~~said the~~ first independent clamp movable in at least one x-axis direction, at least one y-axis direction, and at least one z-axis direction; and positioning a second independent clamp over another portion of ~~said the~~ lead finger for restraining ~~said the~~ lead finger in a position on a portion of ~~said the~~ heat block for ~~said~~ bonding of ~~said the~~ wire thereto, ~~said the~~ second independent clamp movable in ~~said the~~ at least one x-axis direction, ~~said the~~ at least one y-axis direction, and ~~said the~~ at least one z-axis direction.

10. (Currently Amended) The method of claim 9, further comprising: actuating an apparatus for bonding ~~said the~~ portion of ~~said the~~ wire to ~~said the~~ portion of ~~said the~~ lead finger.

11. (Currently Amended) The method of claim 10, further comprising: removing ~~said the~~ second independent clamp from ~~said the another~~ portion of ~~said the~~ lead finger before removal of ~~said the~~ apparatus from ~~said the~~ lead finger ~~supported on a portion of said heat block.~~

12. (Currently Amended) The method of claim 9, wherein ~~said the~~ second independent clamp comprises a clamp for positioning between ~~said the~~ first independent clamp and an end of ~~said the~~ lead finger.

13. (Currently Amended) The method of claim 9, wherein ~~said the~~ first independent clamp and ~~said the~~ second independent clamp each comprise ~~an a clamp that is~~ independently movable ~~clamp~~ with respect to each other ~~clamp~~ and ~~said the~~ lead finger.